

## Device Selection Guide

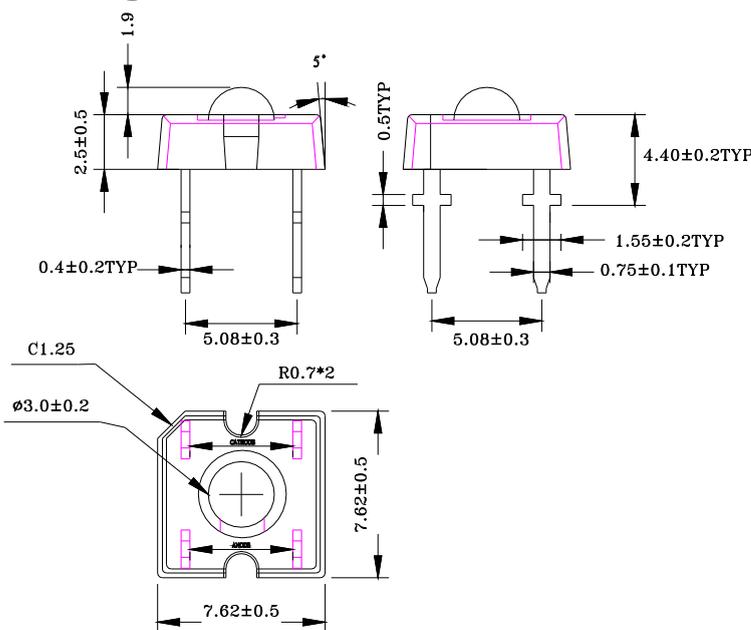
**PRELIMINARY**

Part Number EOZ-	Total Flux $\Phi_V(\text{mlm})^{[1]}$ @ $I_F = 70 \text{ mA}$		Viewing Angle $2\theta_{1/2}$	Dominant Wavelength $\lambda d(\text{nm}) @ I_F = 70 \text{ mA}$	$V_F$ @ $I_F = 70 \text{ mA}$		$I_R(\mu\text{A})$ @ $V_R = 10\text{V}$
	Min.	Typ.	Typ.	Typ.	Typ.	Max.	Max.
ZBRHCD0-DG	1000	1700	40°	623	2.3	2.6	100

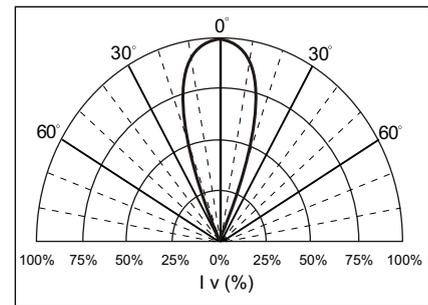
BIN#	B	C	D*
Total Flux(mlm) @ $I_F = 70 \text{ mA}$	1000-1430	1430-2000	2000-2750

Notes: [1] Tolerance Value of  $\Phi \pm 15\%$ .

## Package Dimensions



## Beam Pattern



Note:

- All dimensions are in millimeters.
- Tolerance is  $\pm 0.20\text{mm}$  unless otherwise noted.
- Protruded resin under bottom surface of epoxy is 1.5mm max.
- Lead spacing is measured where the leads emerge from the package
- Specifications are subject to change without notice.

## Absolute Maximum Ratings at $T_A = 25^\circ\text{C}$

Parameter	Symbol		<i>USER---APPROVED</i>
DC Forward Current	$I_f$	70mA	
Reverse Voltage	$V_r$	10V	
Power Dissipation	$P_D$	182mW	
Operating Temperature Range	$T_{opr}$	-40°C to + 85°C	
Storage Temperature Range	$T_{sto}$	-40°C to + 100°C	
Lead Soldering Temperature	$T_{sol}$	260°C for 5 Seconds	

Notes: Duty Ratio=1/10, Pulse Width=0.1 ms